

Q7800 Automatic Wedge Bonder

Designed for Complex Hybrid, Opto-Electronic and I.C. Assembly Requirements

Specifications*

Standard Features – Hardware

Rotary Bond Head
On-Axis Linear Theta Encoder
4" X 3.65" table travel
Programmable U/S Generator
Matrox Pattern Recognition System
Flat Panel Monitor
Stereo Zoom 4 Microscope
Wireless Mouse
Galil Motion Control System
Windows™ XP OS
Fiber Optic Light Source

Specifications

Wire - Aluminum or Gold
Size Range
0.0007" – 0.003" (17.8 – 76.2 microns)
Maximum Wires Per Device
Unlimited

Spool Diameter
2.0" (50.8)

Wire Feed Angle
30°, 38°, 45°, 60°

Bonding Speed per Wire
600 ms pending application

XY Table
Resolution
± 0.0000625" (1.6 microns)
Bonding Pitch
± 0.00275" (69.9 microns)

* Subject to Change

12/01/14

Standard Features – Software

Point and Click Bond Targeting
Simple, Intuitive Programming
Easy Bond Process Editing
Extensive Program Storage
Bond Parameter Library
Unlimited Wire Program Storage
Table Tear Capability
Multiple Stitch Bonding
Program Wire Groups for Multi-device,
High Wire Count Hybrids

Options

Custom Software
Programmable Temperature Controller
Universal Workholder – Heated or Ambient
Additional Fiber Optic Light Source

Accessories

Ethernet Adapter for Networking Bonders

Miscellaneous

Remote Diagnostics Capability
CE Mark

Facilities

Electric - 120 VAC, 50/60 Hz, 15A
N2 or clean, dry air for gold wire
Vacuum / Air as required for workholder

Dimension/Weight

Height: 72" (183 cm)
Width: 39" (99 cm)
Depth: 34.5" (88 cm)
Table Height: 40" (102 cm)
Weight: 600 pounds (273 Kg)
Crated Weight: 750 pounds (341 Kg)